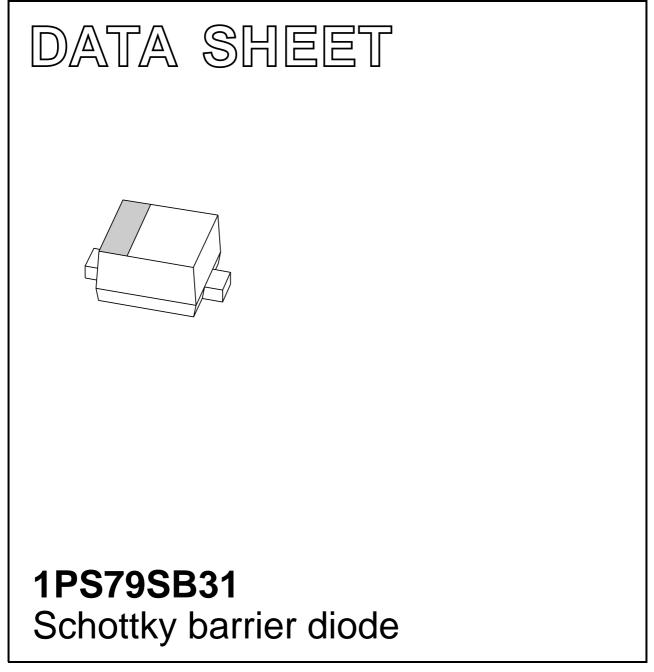
DISCRETE SEMICONDUCTORS



Product data sheet

2002 Jan 11



1PS79SB31

Schottky barrier diode

FEATURES

- Very low forward voltage
- Guard ring protected
- Ultra small SMD package.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Low current rectification
- Low power consumption applications (e.g. hand-held devices).

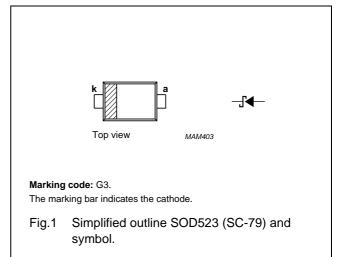
DESCRIPTION

Planar Schottky barrier diode in a SOD523 (SC-79) ultra small SMD plastic package.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		-	30	V
I _F	continuous forward current		-	200	mA
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ s}; \delta \le 0.5$	-	300	mA
I _{FSM}	non-repetitive peak forward current	t = 8.3 ms half sine wave; JEDEC method	-	1000	mA
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	125	°C
T _{amb}	operating ambient temperature		-65	+125	°C



Schottky barrier diode

1PS79SB31

ELECTRICAL CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	see Fig.2;			
		I _F = 0.1 mA	130	190	mV
		I _F = 1 mA	190	250	mV
		I _F = 10 mA	255	300	mV
		I _F = 100 mA	355	410	mV
		I _F = 200 mA	420	500	mV
I _R	continuous reverse current	V _R = 10 V; note 1; see Fig.3	2.5	30	μA
C _d	diode capacitance	$V_R = 1 V$; f = 1 MHz; see Fig.4	20	25	pF

Note

1. Pulse test: t_p = 300 µs; δ = 0.02.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	450	K/W

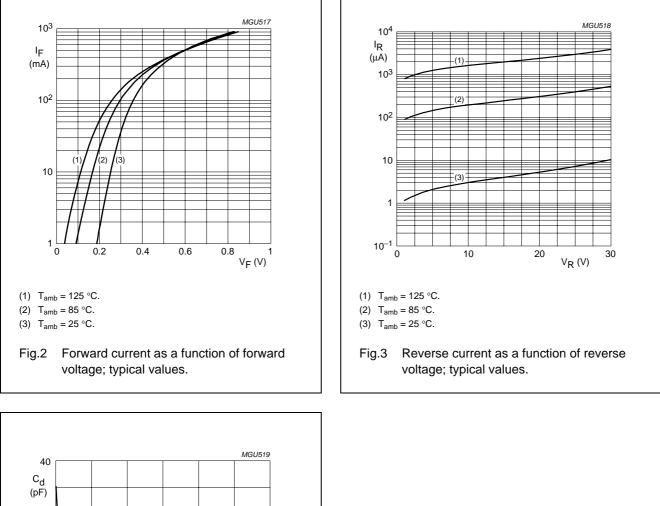
Note

1. Refer to SC-79 (SOD523) standard mounting conditions.

Schottky barrier diode

1PS79SB31

GRAPHICAL DATA



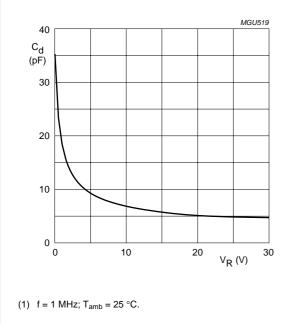


Fig.4 Diode capacitance as a function of reverse voltage; typical values.

Product data sheet

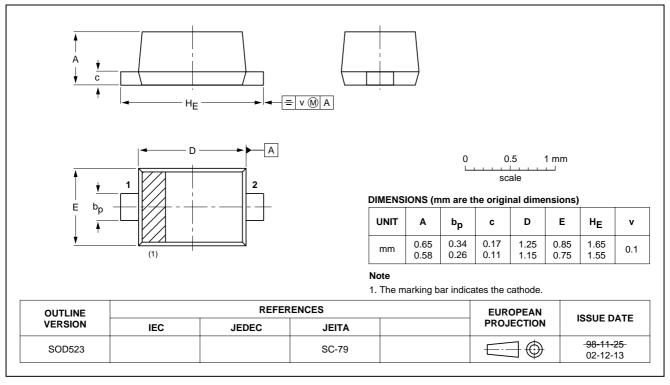
SOD523

Schottky barrier diode

1PS79SB31

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads



Schottky barrier diode

1PS79SB31

DATA SHEET S	STATUS
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DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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